

# Agilent M9703A AXIe Digitizer

# **Product Security Document**





### Notices

© Agilent Technologies, Inc. 2011

No part of this manual may be reproduced in any form or by any means (including electronic storage and retrieval or translation into a foreign language) without prior agreement and written consent from Agilent Technologies, Inc. as governed by United States and international copyright laws.

#### Manual Part Number M9703-90004

#### Edition

Edition 1.0, January 2012 Agilent Technologies, Inc.

#### **Sales and Technical Support**

To contact Agilent for sales and technical support, refer to the "support" links on the following Agilent web resources:

www.agilent.com/find/Digitizers



 <u>www.agilent.com/find/assist</u> (worldwide contact information for repair and service)



#### Warranty

The material contained in this document is provided "as is," and is subject to being changed, without notice, in future editions. Further, to the maximum extent permitted by applicable law, Agilent disclaims all warranties, either express or implied, with regard to this manual and any information contained herein, including but not limited to the implied warranties of merchantability and fitness for a particular purpose. Agilent shall not be liable for errors or for incidental or consequential damages in connection with the furnishing, use, or performance of this document or of any information contained herein. Should Agilent and the user have a separate written agreement with warranty terms covering the material in this document that conflict with these terms, the warranty terms in the separate agreement shall control.

### Product Declassification and Security

The following products / families are covered by this document:

Model Number(s):

M9703A

**Product Name:** 

AXIe Digitizer

# **Table of Contents**

Introduction	5
Terms and Definitions	5
Instrument Memory.	6
Instrument memory locations - Base Instrument	6
Memory Clearing, Sanitization and/or Removal Procedures	
Volatile Memories	9
Non User-accessible Memories	9
Non-volatile, User-accessible Memories.	
Procedure for Declassification of a Faulty Instrument	10
References	11

### Introduction

This document details the internal memory locations of the instrument and describes instrument security features and the steps to declassify an instrument through memory sanitization or removal. For additional information on a particular product, the Agilent Instrument Security Database may be accessed here: <a href="http://www.agilent.com/find/security">www.agilent.com/find/security</a> For general information the Agilent Aerospace and Defense web page may be found here: <a href="http://www.agilent.com/find/ad">www.agilent.com/find/security</a>

### **Terms and Definitions**

Clearing	Clearing is the process of eradicating the data on media before reusing the media so that the data can no longer be retrieved using the standard interfaces on the instru- ment. Clearing is typically used when the instrument is to remain in an environment with an acceptable level of protection. As defined in Section 8-301a of DoD 5220.22- M, "National Industrial Security Program Operating Manual (NISPOM)",
Instrument Declassification	A term that refers to procedures that must be undertaken before an instrument can be removed from a secure environment, such as is the case when the instrument is returned for calibration. Declassification procedures include memory sanitization or memory removal, or both. Agilent declassification procedures are designed to meet the requirements specified in DoD 5220.22-M (NISPOM), Chapter 8.
Sanitization	Sanitization is the process of removing or eradicating stored data so that the data can- not be recovered using any known technology. Instrument sanitization is typically required when an instrument is moved from a secure to a non-secure environment such as when it is returned to the factory for calibration. (The instrument is declas- sified) Agilent memory sanitization procedures are designed for customers who need to meet the requirements specified by the US Defense Security Service (DSS). These requirements are outlined in the "Clearing and Sanitization Matrix" issued by the Cog- nizant Security Agency (CSA) and referenced in National Industrial Security Program Operating Manual (NISPOM) DoD 5220.22M ISL 01L-1 section 8-301.
Secure Erase	Secure Erase is a term that is used to refer to either the clearing or sanitization features of Agilent instruments.

### **Instrument Memory**

This section contains information on the types of memory available in your instrument. It explains the size of memory, how it is used, its location, volatility, and the sanitization procedure.

### **Instrument memory locations - Base Instrument**

Description	PCIe configuration memory
Purpose / Contents	Options, Module capability, Serial number
Size / Technology	4 kb EEPROM
Location in instrument	Base card
Written by	Factory only
User accessible?	No
Sanitization method	None
Non-volatile?	Yes

Description	Parameter storage
Purpose / Contents	Factory calibration/configuration data, look-up table.
Size / Technology	1 Mb EEPROM
Location in instrument	Base card
Written by	Factory only
User accessible?	No
Sanitization method	None
Non-volatile?	Yes

Description	PCIe Switch configuration memory
Purpose / Contents	PCIe switch configuration
Size / Technology	256 kb EEPROM
Location in instrument	Base board, on PCIe switch IC
Written by	Factory only
User accessible?	Νο
Sanitization method	None
Non-volatile?	Yes

Description	FRU ID memory
Purpose / Contents	AXIe product FRU ID
Size / Technology	256 kb
Location in instrument	Base card
Written by	Factory only
User accessible?	Νο
Sanitization method	None
Non-volatile?	Yes

Description	Front End parameter memory
Purpose / Contents	Channel parameters
Size / Technology	4x 1 Mb EEPROM's
Location in instrument	On FE mezzanine cards
Written by	Factory only
User accessible?	No
Sanitization method	None
Non-volatile?	Yes
Remarks	One per mezzanine card (4x)

Description	Control FPGA firmware memory
Purpose / Contents	Instrument operation, Control FPGA firmware
Size / Technology	128 Mb Flash
Location in instrument	Base card
Written by	Factory, Support, or User firmware upgrade via SFP application.
User accessible?	Νο
Sanitization method	None
Non-volatile?	Yes

Description	DPU FPGA firmware memory
Purpose / Contents	Instrument operation, DPU (channel) FPGA firmware
Size / Technology	4 Gb NAND Flash
Location in instrument	Base card
Written by	Factory, User via SFP application.
User accessible?	Yes
Sanitization method	Erase / Overwrite data (See "Memory Clearing, Sanitization and/or Removal Pro- cedures" on page 9)
Non-volatile?	Yes
Remarks	Contains standard DPU firmware and/or User generated custom firmware

Description	Measurement data memory
Purpose / Contents	Measurment data acquired during operation
Size / Technology	4x 1 Gb DRAM's
Location in instrument	Base card
Written by	Acquisition operation
User accessible?	Yes
Sanitization method	Power removal
Non-volatile?	Νο
Remarks	1 Gb per mezzanine card (4x).

Description	Measurement data buffer
Purpose / Contents	Mesururement data buffer used during operation
Size / Technology	4x 36 Mb SRAM's
Location in instrument	Base card
Written by	Acquisition operation
User accessible?	Yes
Sanitization method	Power removal
Non-volatile?	Νο
Remarks	36 Mb per mezzanine card (4x).

### Memory Clearing, Sanitization and/or Removal Procedures

This section explains how to clear, sanitize, and remove memory from you instrument for any non-volatile memory location that can be written to during normal operation.

### **Volatile Memories**

The volatile memory in the instrument does not retain any information when power is removed from the instrument. Therefore sanitization may be achieved by removal of the instrument power.

### Non User-accessible Memories

Since these locations may only be programmed by Agilent Technologies in the factory, they cannot contain any user or acquisition data. It is therefore not necessary to perform any sanitization on these areas.

Memory	DPU FPGA firmware memory
Description / Purpose	Instrument operation, DPU (channel) FPGA firmware
Size	4 Gb NAND Flash
Clearing procedure	Using the Agilent SFP application, from the 'File' menu select the 'Load from or Save to FPGA/CPLD/EEPROM' function. A window will open showing the accessible memory devices on the instrument. The user accessible memory areas are: • FPGADevice 1 to 4 • FlashConfig 1 to 7 (28 locations in total) • Flash Storage • UserZone 1 • UserZone 2 • UserZone 3 • UserZone 4 Select each of the above in turn and press the 'Erase' button on the right hand panel. A confirmation dialog will appear confirming the operation.
Sanitization procedure	There is currently no automated method of providing sanitization of the memory areas. However the user may implement any required mentod by making successive write oper- ations to each location. Using the method detailed above for clearing, but instead of performing an erase, write to each area in turn with the required data patterns.
Memory removal	This memory can not be removed without damaging the instrument
Write protecting	Not applicable

### Non-volatile, User-accessible Memories

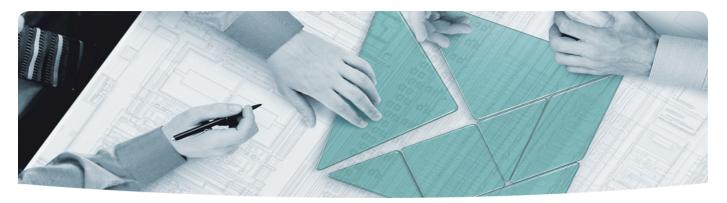
### **Procedure for Declassification of a Faulty Instrument**

If the instrument is malfunctioning to the degree that it is not possible to communicate with it via the SFP application it will not be possible to use the clearing or sanitization procedures detailed. It is also not possible to remove the useraccessible memory integrated circuits without causing damage to the instrument.

Therefore declassification of a faulty instrument will require secure destruction of that instrument.

### References

- 1 DoD 5220.22-M, "National Industrial Security Program Operating Manual (NISPOM)"United States Department of Defense. Revised February 28, 2006. May be downloaded in Acrobat (PDF) format from: www.dss.mil/isp/fac\_clear/download\_nispom.html
- 2 ODAA Process Guide for C&A of Classified Systems under NISPOM Defense Security Service. DSS-cleared industries may request a copy of this document via email, by following the instructions at: http://www.dss.mil/isp/odaa/request.html



#### The Modular Tangram

The four-sided geometric symbol that appears in Agilent modular product literature is called a tangram. The goal of this seven-piece puzzle is to create shapes-from simple to complex. As with a tangram, the possibilities may seem infinite as you begin to create a new test system. With a set of clearly defined elementshardware, software—Agilent can help you create the system you need, from simple to complex.



#### **DISCOVER** the Alternatives ...

... Agilent MODULAR Products

Agilent Advantage Services is committed to your success throughout your equipment's lifetime. www.agilent.com/find/advantageservices



Agilent Email Updates keep you informed on the latest product, support and application information. www.agilent.com/find/emailupdates



Agilent Channel Partners provide sales and solutions support. For details, see www.agilent.com/find/channelpartners



KEMA Certified ISO 9001:2008 certified. For details, see ISO 9001:2008 www.agilent.com/quality



PICMG and the PICMG logo, CompactPCI and the CompactPCI logo, AdvancedTCA and the AdvancedTCA logo are US registered trademarks of the PCI Industrial Computers Manufacturers Group. "PCIe" and "PCI EXPRESS" are registered trademarks and/or service marks of PC-SIG. Microsoft, Windows, Visual Studio, Visual C++, Visual C#, and Visual Basic are either registered trademark or trademarks of Microsoft Corporation.

Product descriptions in this document are subject to change without notice.

© Agilent Technologies, Inc. 2010-2011

### www.agilent.com www.agilent.com/find/modular www.agilent.com/find/security

For more information on Agilent Technologies' products, applications or services, please contact your local Agilent office. (For additional listings, go to www.agilent.com/find/assist.)

#### Americas

Americas	
Canada	(877) 894 4414
Brazil	(11) 4197 3500
Mexico	01800 5064 800
United States	(800) 829 4444
Asia Pacific	
Australia	1 800 629 485
China	800 810 0189
Hong Kong	800 938 693
India	1 800 112 929
Japan	0120 (421) 345
Korea	080 769 0800
Malaysia	1 800 888 848
Singapore	1 800 375 8100
Taiwan	0800 047 866
Thailand	1 800 226 008
Europe & Middle East	
Austria	43 (0) 1 360 277 1571
Belgium	32 (0) 2 404 93 40
Denmark	45 70 13 15 15
Finland	358 (0) 10 855 2100
France	0825 010 700 (0.125 €/minute)
Germany	49 (0) 7031 464 6333
Ireland	1890 924 204
Israel	972 3 9288 504 / 544
Italy	39 02 92 60 8484
Netherlands	31 (0) 20 547 2111
Spain	34 (91) 631 3300
Sweden	0200 88 22 55
Switzerland	0800 80 53 53
United Kingdom	44 (0) 118 9276201



### **Agilent Technologies**